



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AF/IFW

In re Applicant:

Joseph M. Steigerwald

§ Art Unit: 2815  
§ Examiner: Sheila V. Clark  
§ Atty Docket: ITL.0947US  
§ P15971  
§ Assignee: Intel Corporation

Serial No.: 10/722,801

Filed: November 26, 2003

For: Electrochemically Polishing Conductive  
Films on Semiconductor Wafers

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**REPLY TO FINAL REJECTION**

Sir:

In response to the final rejection mailed April 19, 2005, please amend the above-referenced patent application as follows:

Date of Deposit: May 4, 2005  
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

*Cynthia L. Hayden*  
Cynthia L. Hayden

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MAY 06 2005  
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